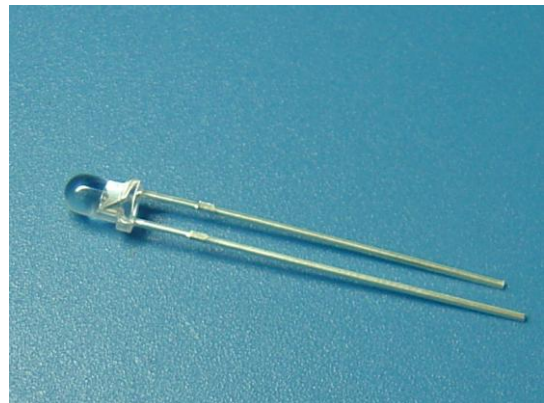


**ATTENTION**  
OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

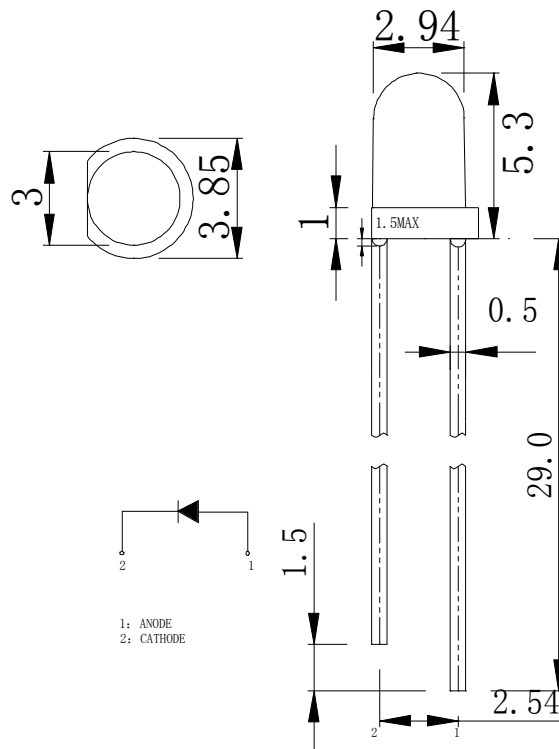
**Features**

- φ 3 LAMP LED
- LOW POWER CONSUMPTION.
- CABINED VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- PACKAGE: 1000PCS / BAG.

**HL-308H203BC**



**Package Dimensions**



**Description**

This devices are made with TS GaN.

Tolerance Grade	Dimension Tolerance (UNIT:mm)			
	0.5~3	3~6	6~30	30~120
	±0.1	±0.2	±0.3	±0.5
Chip		Lens Color		
Material	Emitting Color	Water Clear		
GaN	Blue			

**■ Absolute Maximum Rating**

Item	Symbol	Value	Unit
Forward Current	$I_F$	20	mA
Peak Forward Current*	$I_{FP}$	100	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	80	mW
Electrostatic discharge	$E_{SD}$	600	V
Operation Temperature	$T_{opr}$	-30~+80	°C
Storage Temperature	$T_{stg}$	-30~+80	°C
Lead Soldering Temperature*	$T_{sol}$	Max. 260°C for 5sec Max.	

\* $I_{FP}$  Conditions: Pulse Width  $\leq 10$ msec

\* $T_{sol}$  Conditions: 3mm from the base of the epoxy bulb

**■ Typical Optical/ Electrical Characteristics  $T_a=25^\circ\text{C}$** 

Item	Symbol	Condition	Rank	Min.	Typ.	Max.	Unit
Luminous Intensity	$I_v$	$I_F=20\text{mA}$	V	2230		2900	mcd
			W	2900		3770	mcd
			X	3770		4900	mcd
			Y	4900		6370	mcd
Forward Voltage	$V_F$			2.8	3.2	3.6	V
Viewing Angle	$2\theta$ 1/2			--	25	--	deg
Dominant Wavelength	$\lambda_D$			465	--	475	nm
Recommend Forward Current	$I_F(\text{rec})$	--		--	--	20	mA
Reverse Current	$I_R$	$V_r=5\text{V}$		--	--	10	$\mu\text{A}$

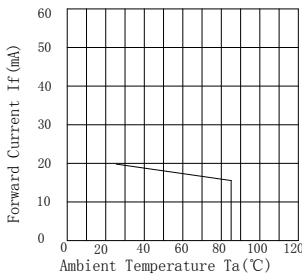
Notes:

Tolerance :  $V_F \pm 0.1\text{V}$ ,  $\lambda_d \pm 2\text{ nm}$ ,  $I_V(\phi V) \pm 15\%$ ,  $2\theta$  1/2  $\pm 15\%$

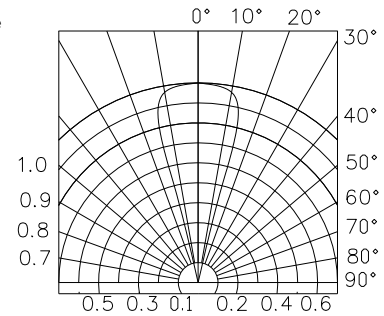
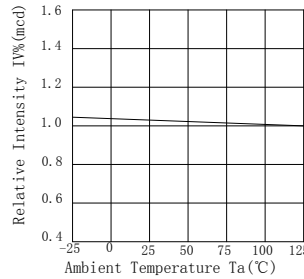
**Reliability Performance  
 Test Items And Result**

Test Classification	Test Item	Test Conditions	Test Duration	Sample Size	AC/RE
Life Test	Room Temperature DC Operating Life Test	$T_a=25^{\circ}\text{C}\pm 5^{\circ}\text{C}$ , $I_F=20\text{mA}$	1000 hrs	22 pcs	0/1
Environment Test	High Temperature & High Humidity Test	$85^{\circ}\text{C}\pm 5^{\circ}\text{C}/85\% \text{RH}$ $I_F=5\text{mA}$	1000 hrs	22 pcs	0/1
	High Temperature Storage	$T_a=100^{\circ}\text{C}\pm 5^{\circ}\text{C}$	1000 hrs	22 pcs	0/1
	Low Temperature Storage	$T_a=-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$	1000 hrs	22 pcs	0/1
Mechanical Test	Resistance to Soldering Heat	Temp= $260^{\circ}\text{C}$ max T=5sec max	1times	22 pcs	0/1
	Lead Integrity	Load 2.5N(0.25kgf) $0^{\circ} \sim 90^{\circ} \sim 0^{\circ}$	3times	22 pcs	0/1

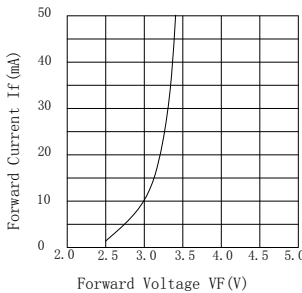
Forward Current vs. Ambient Temperature



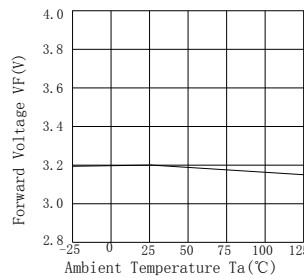
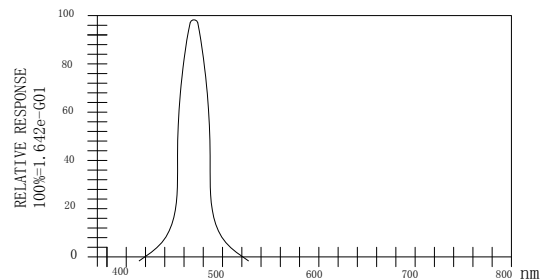
Relative Intensity vs. Ambient Temperature



Forward Current vs. Forward Voltage



Forward Voltage vs. Ambient Temperature


 Luminous Spectrum ( $T_a=25^{\circ}\text{C}$ ) SPECTRAL RADIANCE


## Soldering:

### 1. Manual Of Soldering

The temperature of the iron tip should not be higher than 300°C and Soldering within 3 seconds per solder-land is to be observed.

### 2. DIP soldering (Wave Soldering):

Preheating: 120°C~150°C, within 120~180 sec.

Operation heating: 245°C ±5°C within 5 sec. 260°C (Max)

Gradual Cooling (Avoid quenching).

